

# SMC

**Plastic, surface-mounted package; 2 terminals;  
6.86 mm x 6.11 mm x 2.34 mm body**

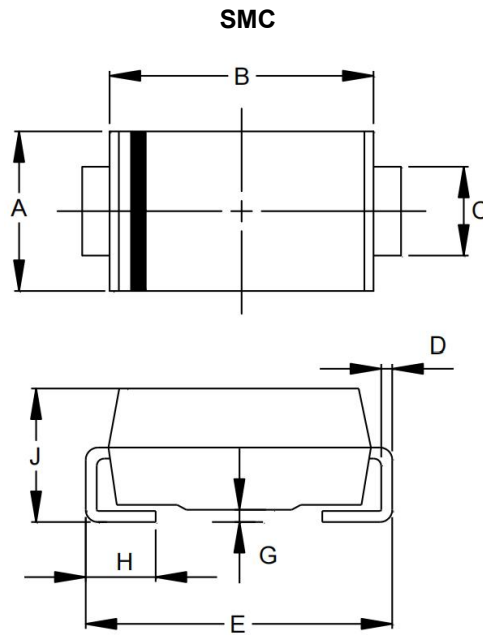
**塑料表面贴装封装；2 引脚；**

**封装本体尺寸 6.86 mm x 6.11 mm x 2.34 mm**

## 1. Mechanical Data 封装数据

Feature 特性	Description 描述
Package 封装	SMC(DO-214AB)
Moisture Sensitivity Level 湿敏感度等级	J-STD-020 MSL1
Mounting Method Type 安装方式类型	Surface Mount Package 表面贴装封装
Material 材料	Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0. 模塑塑料封装，“绿色”成型复合材料；UL 可燃性等级 94V-0。
Dimensions 尺寸	6.86mm × 6.11mm × 2.34mm body 封装本体（不含引脚）尺寸为 6.86mm × 6.11mm × 2.34mm
Terminals Compliance 引脚合规	2 terminals, Tin Plated Leads, Solderable per MILSTD-202, Method 208 <sup>Ⓔ</sup> 2 个镀锡引脚，可焊性符合 MIL-STD-202 标准中 208 方法 e3 条款的要求
Weight 重量	0.235 grams (Approximate) 约 0.235 克

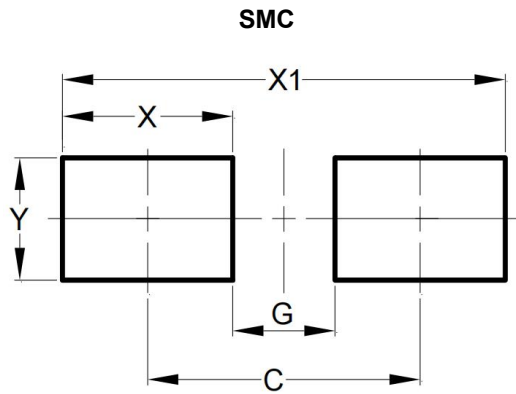
## 2. Package Outline Dimensions 封装外形尺寸



Symbol 符号	Millimeters 毫米	
	Min.最小值	Max.最大值
A	5.59	6.22
B	6.6	7.11
C	2.75	3.15
D	0.15	0.31
E	7.75	8.13
G	-	0.203
H	0.76	1.27
J	2	2.62



### 3. Suggested Pad Layout 推荐焊盘布局



Dimensions 尺寸	Millimeters 毫米
C	6.21
G	4.69
X	1.52
X1	8.13
Y	3.2

Fig. Soldering footprint for SMC

图 SMC 的引脚焊接

### 4. Minimum Packing Quantity 最小包装数量

Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
7	16	850

**Note:**

Package quantities given are for minimum packaging quantity only, not minimum order quantity. For minimum order quantity, please contact Sales Department.

**说明:** 上表所列包装数量仅为最低包装数量，并非最低订购数量。如需最低订购数量，请联系销售部门。



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